

**Features**

- Fast Switching
- Low Gate Charge and  $R_{DS(on)}$
- Low Reverse transfer capacitances

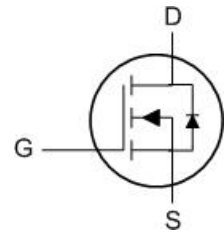
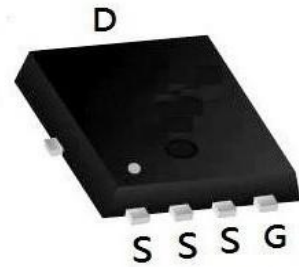

**Product Summary**

BVDSS	RDSON	ID
120V	10.5mΩ	60A

**Applications**

- DC-DC converter
- Portable Equipment
- Power management

**100% DVDS Tested**  
**100% Avalanche Tested**

**PDFN5060-8L Pin Configuration**

**Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	120	V
$V_{GS}$	Gate-Source Voltage	$\pm 20$	V
$I_D@T_C=25^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	60	A
$I_D@T_C=100^\circ C$	Continuous Drain Current, $V_{GS} @ 10V^{1,6}$	35	A
$I_{DM}$	Pulsed Drain Current <sup>2</sup>	220	A
EAS	Single Pulse Avalanche Energy <sup>3</sup>	210	mJ
$I_{AS}$	Avalanche Current	---	A
$P_D@T_C=25^\circ C$	Total Power Dissipation <sup>4</sup>	85	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

**Thermal Data**

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient <sup>1</sup>	---	---	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case <sup>1</sup>	---	1.47	$^\circ C/W$

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA	120	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C, I <sub>D</sub> =1mA	---	---	---	V/°C
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V, I <sub>D</sub> =84A	---	10.5	14	mΩ
		V <sub>GS</sub> =4.5V, I <sub>D</sub> =84A	---	12	16	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.4	1.8	2.2	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	---	---	mV/°C
I <sub>DSS</sub>	Drain-Source Leakage Current	V <sub>DS</sub> =120V, V <sub>GS</sub> =0V, T <sub>J</sub> =25°C	---	---	1	uA
		V <sub>DS</sub> =120V, V <sub>GS</sub> =0V, T <sub>J</sub> =125°C	---	---	100	
I <sub>GSS</sub>	Gate-Source Leakage Current	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =5V, I <sub>D</sub> =84A	---	---	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V, V <sub>GS</sub> =0V, f=1MHz	---	---	---	Ω
Q <sub>g</sub>	Total Gate Charge		---	31	---	nC
Q <sub>gs</sub>	Gate-Source Charge	V <sub>DS</sub> =60V, V <sub>GS</sub> =10V, I <sub>D</sub> =20A	---	9.4	---	
Q <sub>gd</sub>	Gate-Drain Charge		---	7.5	---	
T <sub>d(on)</sub>	Turn-On Delay Time		---	15	---	ns
T <sub>r</sub>	Rise Time	V <sub>DD</sub> =60V, R <sub>G_ext</sub> =5Ω,	---	10	---	
T <sub>d(off)</sub>	Turn-Off Delay Time	V <sub>GS</sub> =10V, I <sub>D</sub> =20A	---	32	---	
T <sub>f</sub>	Fall Time		---	9	---	
C <sub>iss</sub>	Input Capacitance		---	1807	---	pF
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> =60V, V <sub>GS</sub> =0V, f=1MHz	---	212	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	6	---	

**Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,4</sup>	V <sub>G</sub> =V <sub>D</sub> =0V, Force Current	---	---	60	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V, I <sub>S</sub> =84A, T <sub>J</sub> =25°C	---	---	1.4	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =40A, di/dt=100A/μs,	---	60	---	nS
Q <sub>rr</sub>	Reverse Recovery Charge	T <sub>J</sub> =25°C	---	100	---	nC

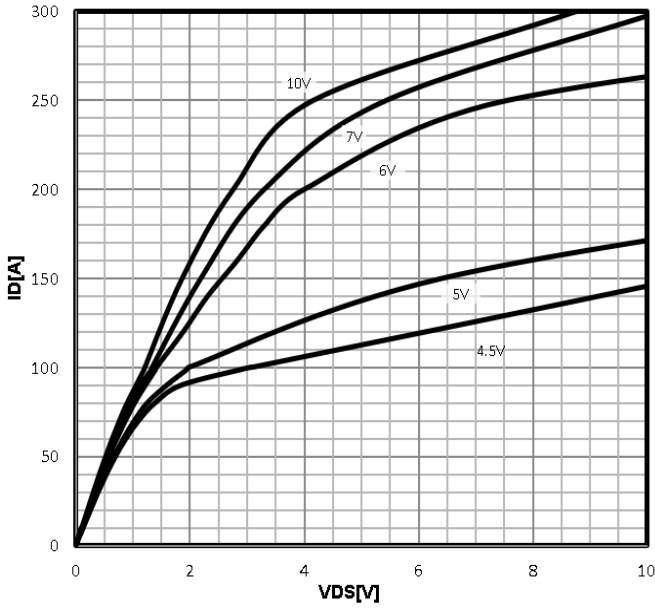
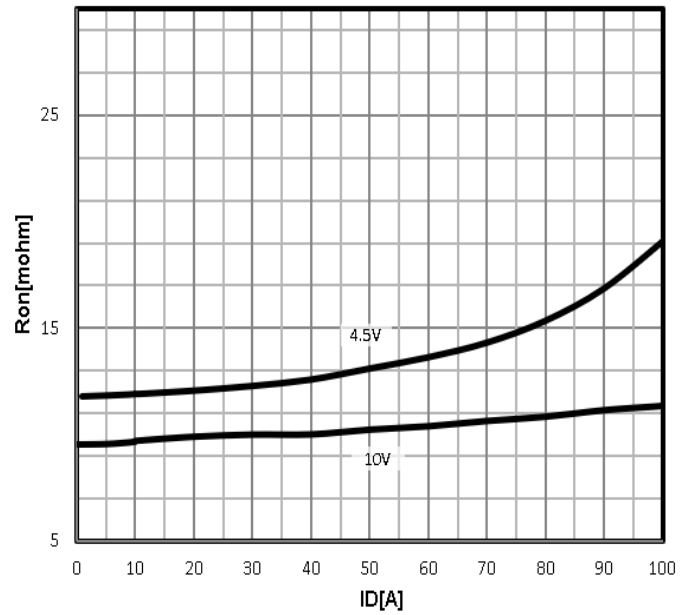
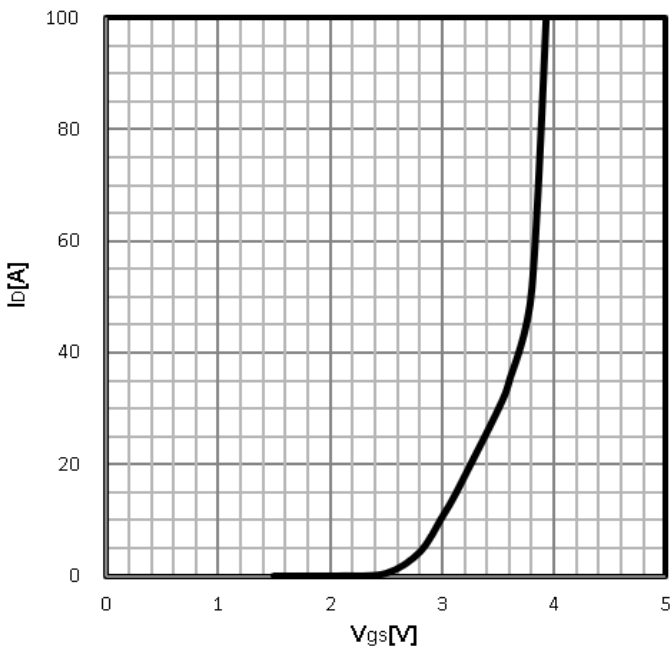
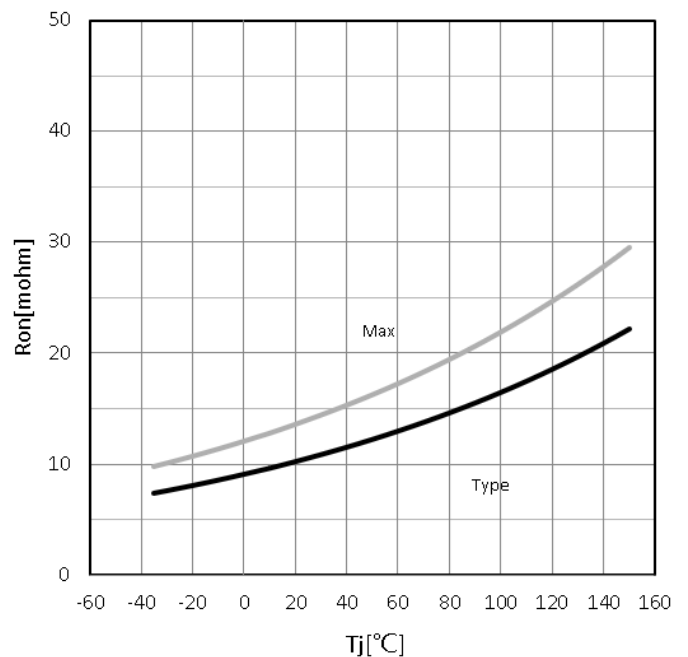
1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.

2. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%

3. The EAS data shows Max. rating. The test condition is V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.5mH,

4. The power dissipation is limited by 150°C junction temperature

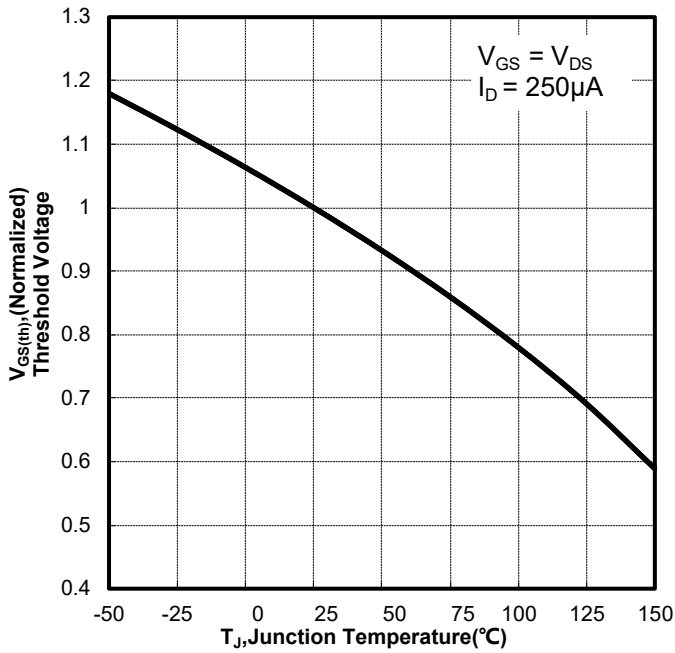
5. The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub>, in real applications, should be limited by total power dissipation.

**Characteristics Curve:**
**Typ. output characteristics**  
 $I_D = f(V_{DS})$ 

**Typ. drain-source on resistance**  
 $R_{DS(on)} = f(I_D)$ 

**Typ. transfer characteristics**  
 $I_D = f(V_{GS})$ 

**Drain-source on-state resistance**  
 $R_{DS(on)} = f(T_j); I_D = 20A; V_{GS} = 10V$ 


**N-Ch 120V Fast Switching MOSFETs**

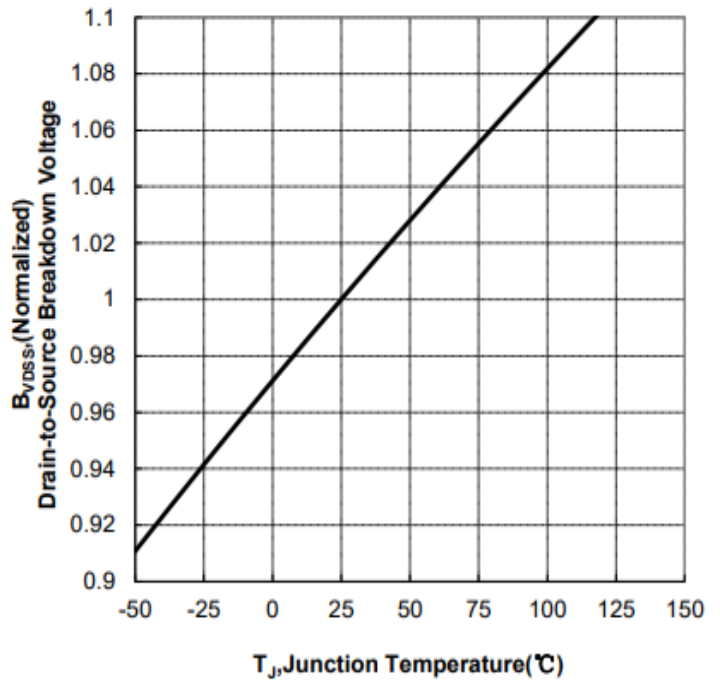
**Gate Threshold Voltage**

$V_{TH}=f(T_j); I_D=250\mu A$



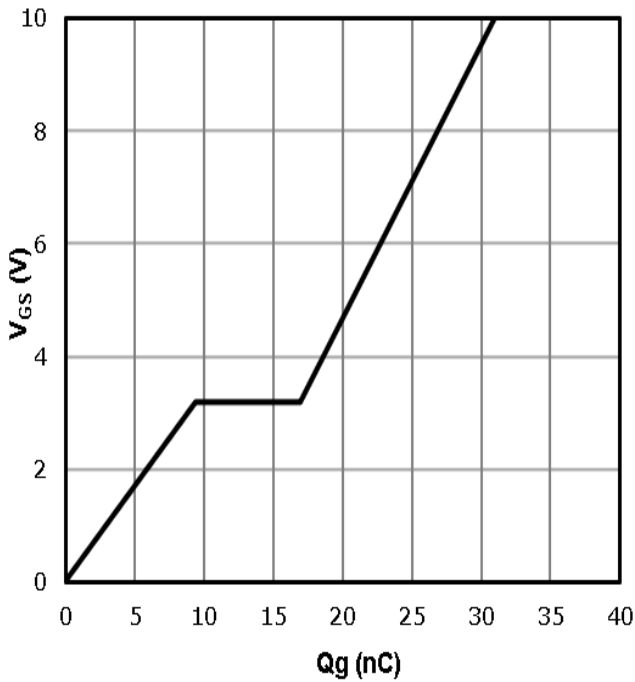
**Drain-source breakdown voltage**

$V_{BR(DSS)}=f(T_j); I_D=250\mu A$



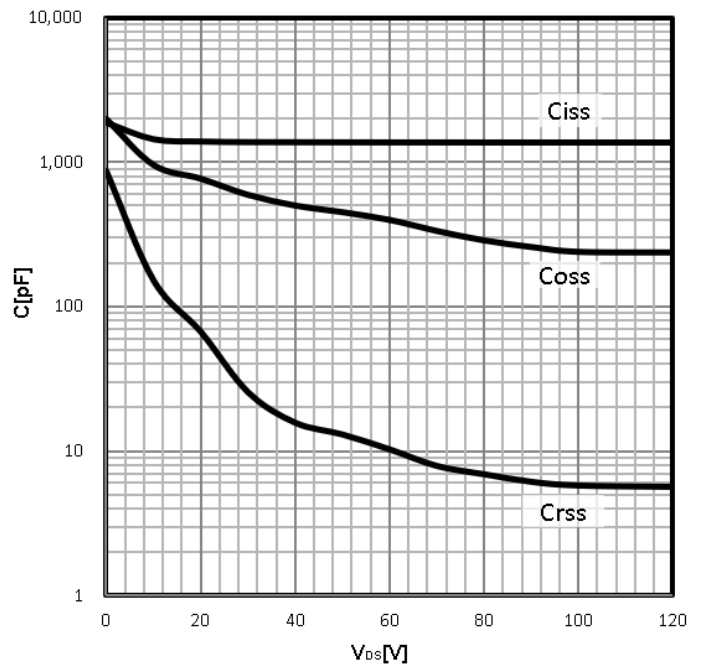
**Typ. gate charge**

$V_{GS}=f(Q_{gate})$

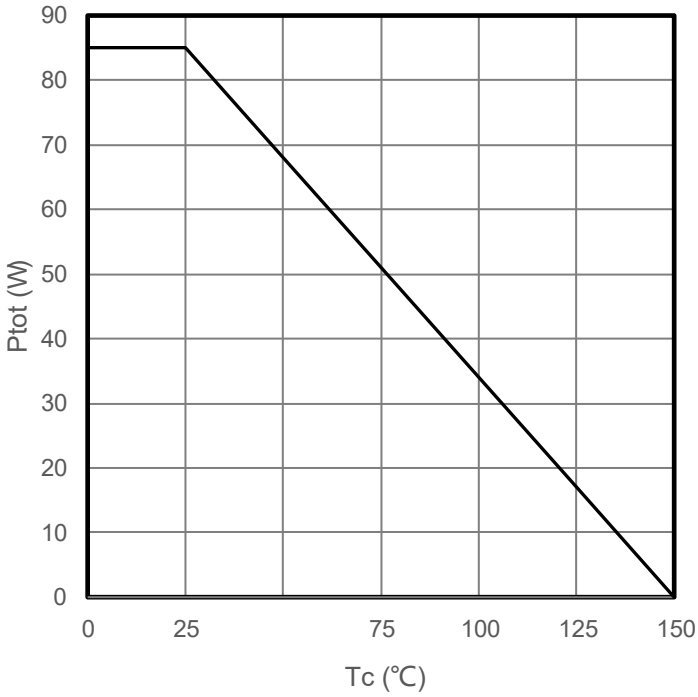


**Typ. capacitances**

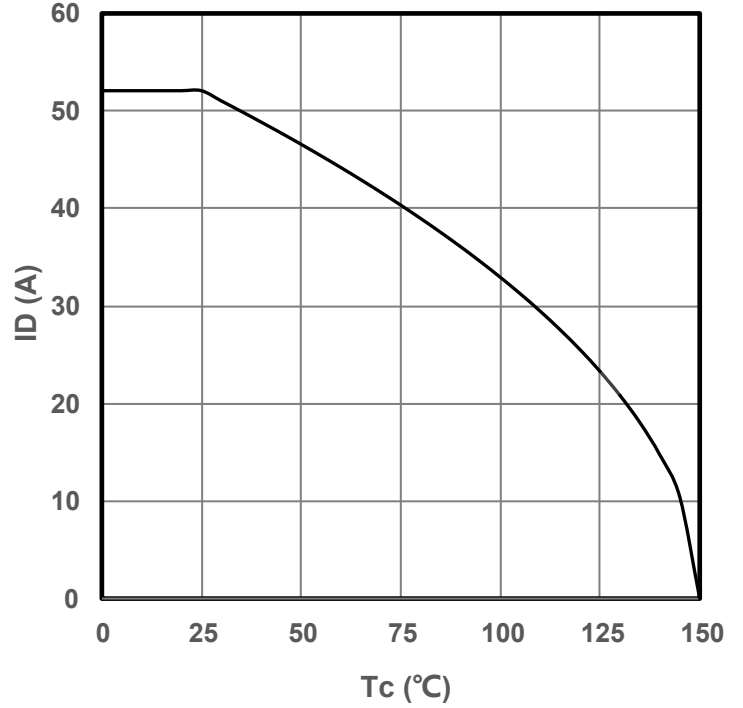
$C=f(V_{DS}); V_{GS}=0V; f$



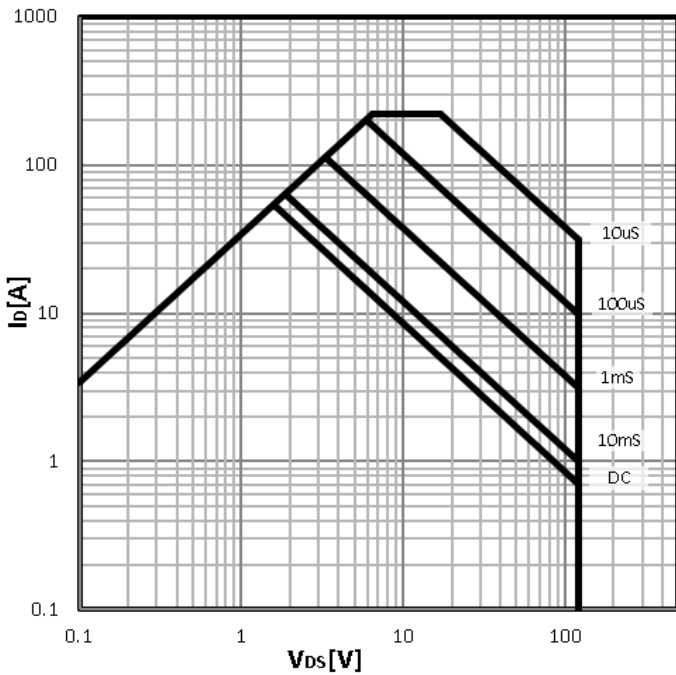
**Power Dissipation**  
 $P_{tot}=f(T_j)$



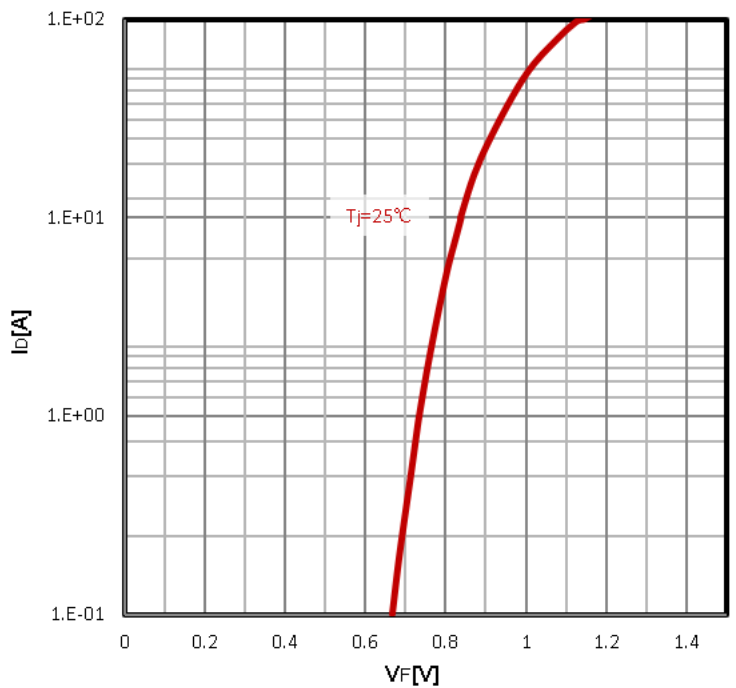
**Maximum Drain Current**  
 $I_D=f(T_c)$



**Safe operating area**  
 $I_D=f(V_{DS})$

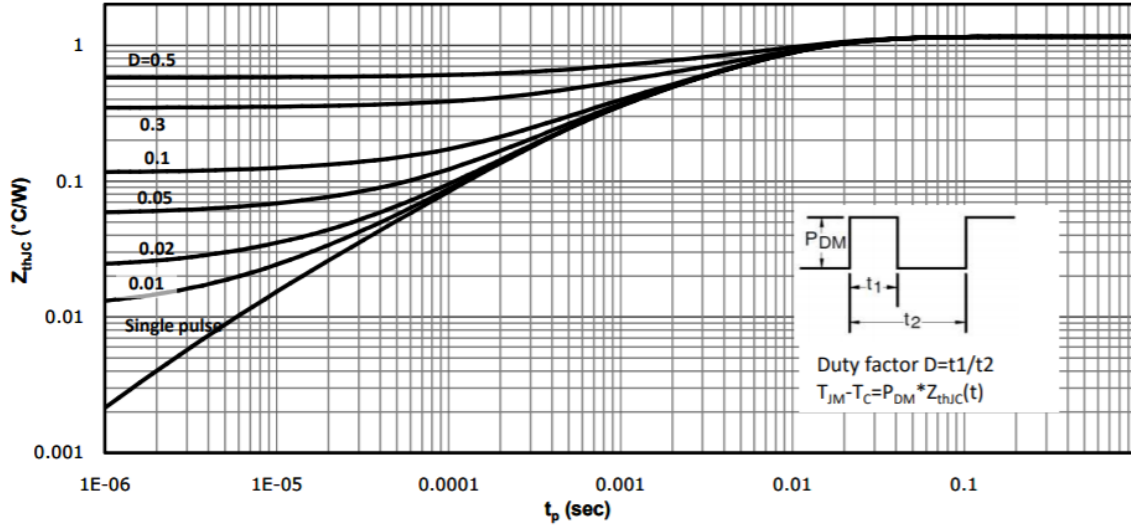


**Body Diode Forward Voltage Variation**  
 $I_F=f(V_{GS})$

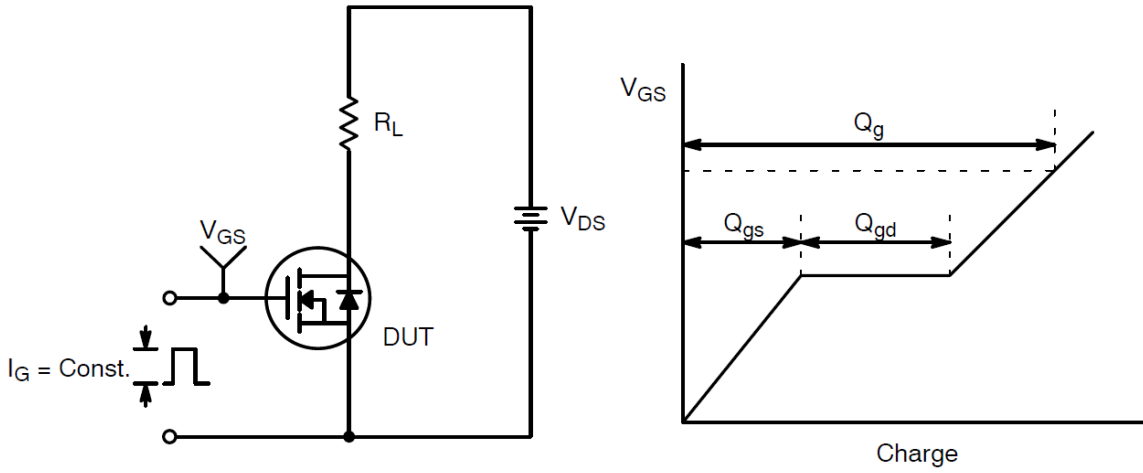


**Max. transient thermal impedance**

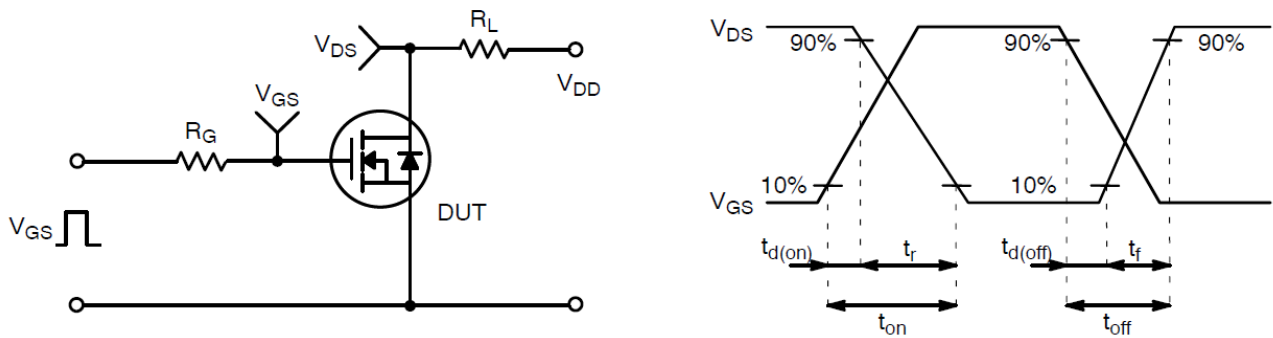
$$Z_{thJC} = f(t_p)$$



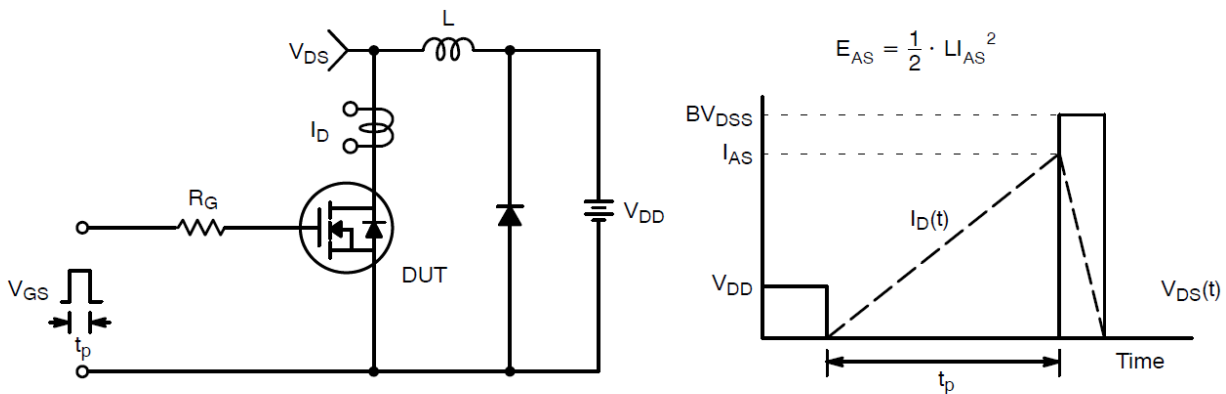
**Test Circuit and Waveform:**



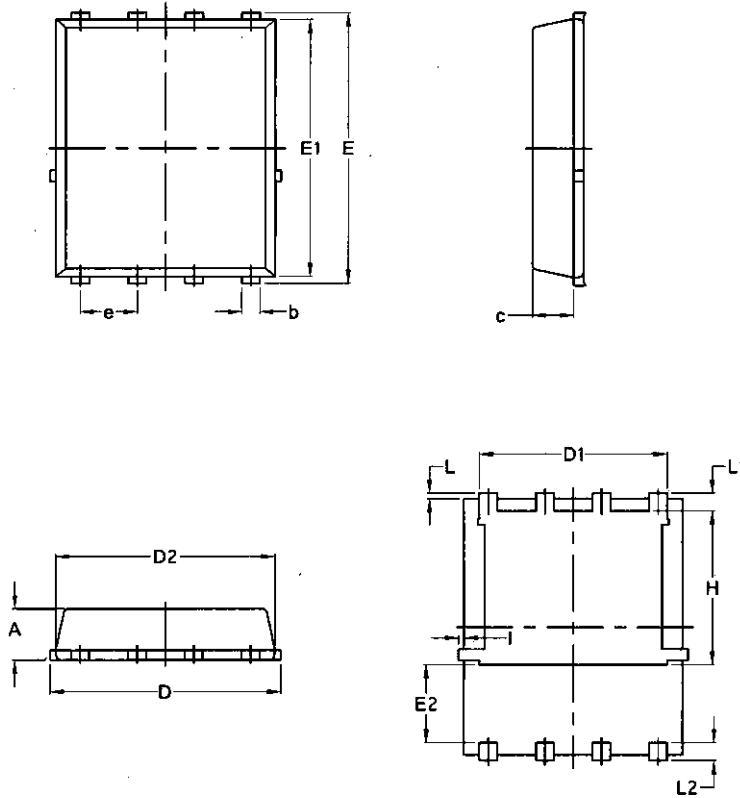
**Gate Charge Test Circuit & Waveform**



**Resistive Switching Test Circuit & Waveforms**



**Unclamped Inductive Switching Test Circuit & Waveforms**

**Package Mechanical Data-PDFN5060-8L-Single**


Symbol	Common			
	mm		Inch	
	Min	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070